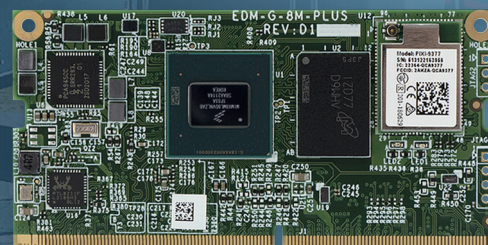


EDM-G-IMX8M-PLUS

- NXP i.MX 8M Plus applications processor
- Up to 4 Cortex-A53 1.8 GHz processors
- Cortex-M7 processor with speeds up to 800 MHz
- Neural Processing Unit (NPU)
- Image Signal Processor (ISP)
- Armv8 64-Bit CPU cores



Specifications

Core System

Processor	NXP i.MX8M Plus
Architecture	ARM Cortex-A53 + M7
AI / ML	NN Accel 2.3 TOPS
PMIC	NXP PCA9450
Memory	Up to 8GB LPDDR4
Storage	32GB eMMC (default)
Board-to-Board Connector	260-pin DDR4 SO-DIMM
System on Module	EDM SOM
Debug Interface	JTAG Interface by Through-hole

Connectivity

Network LAN	1x Realtek RTL8211
Wi-Fi	Qualcomm Atheros QCA9377 Wi-Fi 5 – 802.11 a/b/g/n/ac (optional)
Bluetooth	Qualcomm Atheros QCA9377 Bluetooth (optional)
Antenna	MHF4 connector (optional)

Signaling

HDMI	1x (HDMI 2.0a, up to 4K)
LVDS	1x Dual Channel LVDS (up to 1920×1080)
MIPI DSI	1x Quad Lane MIPI DSI (up to 1920×1080)
MIPI CSI2	2x Quad Lane MIPI CSI-2
LAN	Gigabit with TSN (+2nd RGMII)
PCIe	1 (x1 Gen 3)
USB 3.1	1x Host / 1x OTG (Gen 1)
USB 2.0	1x Host / 1x OTG
I ² S	6x SAI: I2S or AC97
PDM	4x lane
S/PDIF	1x TX/RX
CAN	2x CAN (Commerce Grade) or 2x CAN FD (Industry Grade)
UART	4x
SPI	2x
I ² C	6x
SDIO/SD/MMC	1x
PWM	4x
GPIO	86x
JTAG	thruhole on Module

Video

GPU Engine	GC520L (2D) Vivante GC7000UL
Video decode	1080p60 (h.265, h.264, VP9, VP8)
Video encode	1080p60 (h.265, h.264)
Camera	Dual MIPI CSI (4 lanes)

Audio

Audio Codec	On carrier board
Audio Connectors	I ² S (2 channel)

Power Specifications

Power Input	5V DC +/-5%
Power Consumption	Depending on Configuration

Operation Systems

Standard Support	Linux Yocto Android Ubuntu
Extended Support	Boot2Qt Commercial Linux FreeRTOS Real Time OS

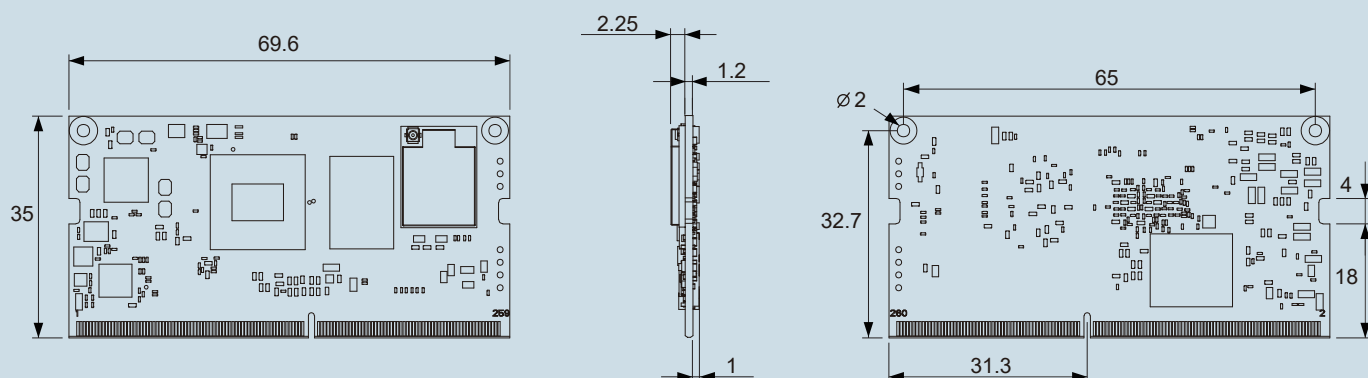
Environmental and Mechanical

Dimensions	69.6 (W) x 35 (H) x 4.45 (D) mm
Form Factor	EDM Type G
Relative Humidity	10 to 90 %
MTBF	100,000+ Hours
Shock	15G half-sine 11 ms duration
Operation Temperature	Commercial: 0° to +60° C Industrial: -40° to +85° C
Vibration	1 Grms random 5-500Hz hr/axis
Weight	8 grams

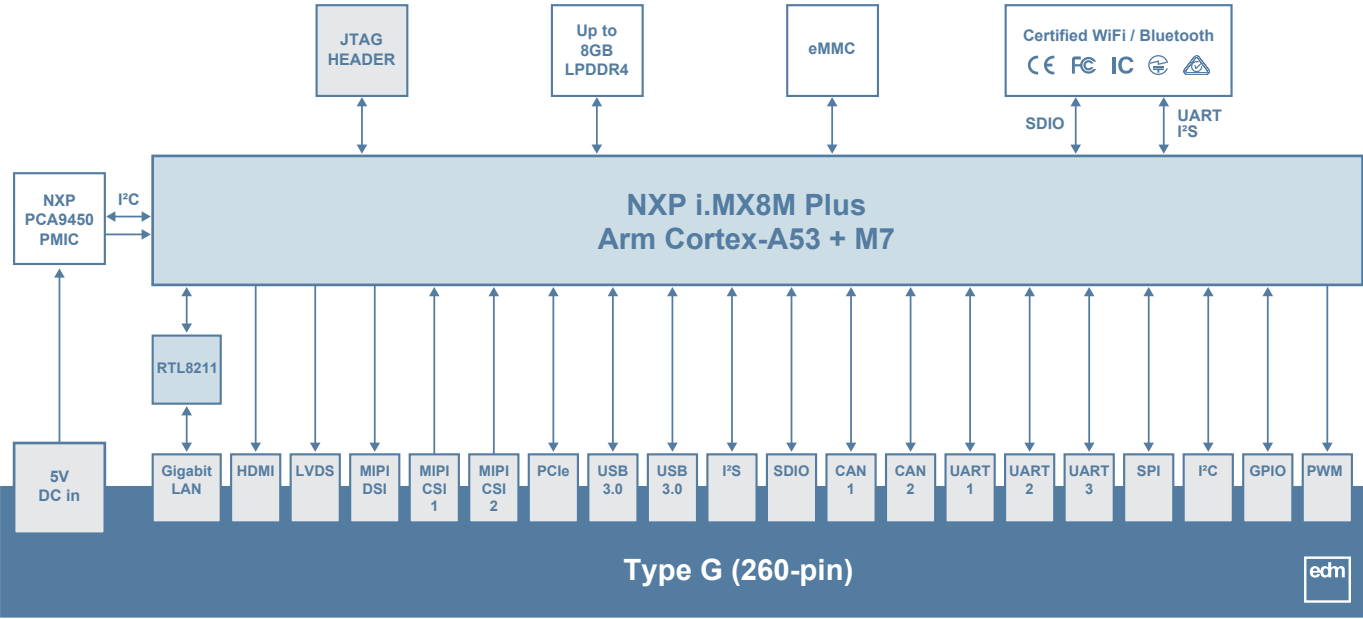
Certification and Compliance

USA	FCC ID: 2AKZA-QCA9377
Canada	IC: 22364-QCA9377
European Union	EN 300 328 v2.2.2 EN 301 893 v2.1.1 EN 55032 / EN 55024
Japan	TELEC: 201-180629
Australia/New Zealand	RCM Compliant
Bluetooth Logo	QDID 150839 (Bluetooth 4.2) QDID 193238 (Bluetooth 5)
Certification	Compliant with RoHS / REACH directives

Dimensions (units in mm)



Block Diagram



Order Information

EDM-G-IMX8MLQ-18-Rxx-Exx-xxxx-xx-xxxx

	Code	Description
Processor	IMX8MLQ	NXP i.MX8M Plus
Processor Speed	16	1.6GHz
	18	1.8GHz
Memory	R10	1GB LPDDR4
	R20	2GB LPDDR4
	R40	4GB LPDDR4
	R60	6GB LPDDR4
	R80	8GB LPDDR4
Storage	E32	eMMC 32GB
	EXX	eMMC other capacity
Wi-Fi / Bluetooth	-	-
	9377	Qualcomm QCA9377 802.11a/b/g/n/ac (2.4 + 5GHz) + Bluetooth
Temperature Range	-	Commercial Temperature range (0° to +60°C)(Default)
	TI	Industrial Temperature range (-40° to +85°C)
Custom ID	XXXX	Custom Part number ID for customized Software loader and special component (BOM)